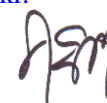


Part Number: Applicable to ASL-series, ABB-series
Product Name: GaAs Amplifier
Package Type: TSSOP24

Package Elements	Constituents	CAS No.	Weight (mg)	Weight %
Active Semiconductor Die	GaAs	1303-00-0	1.12	100
Molding compound	Epoxy Resin	trade secret	3.9685	7.5
	Phenol Resin	trade Secret	1.5874	3.0
	Metal Hydroxide	trade Secret	1.5874	3.0
	Carbon Black	1333-86-4	0.2646	0.5
	Silica A	60676-86-0	42.8599	81.0
	Silica B	7631-86-9	2.6457	5.0
Die attach	Ag	7440-22-4	0.1386	75.5
	acrylic resin	trade secret	0.0266	14.5
	Acrylate A	trade secret	0.0055	3.0
	Acrylate B	trade secret	0.0092	5.0
	Organic Peroxide A	trade secret	0.0018	1.0
	Organic Peroxide B	trade secret	0.0018	1.0
Lead frame	Cu	7440-50-8	31.6791	95.27
	Si	7440-21-3	0.2494	0.75
	Ni	7440-02-0	1.0641	3.2
	Mg	7439-95-4	0.0599	0.18
	Ag	7440-22-4	0.1995	0.6
Tin plating	Tin	7440-31-5	0.9549	100
Gold Wire	Au	7440-57-5	0.0306	100
Total			88.4545	

This information sheet is to declare all substances intentionally added in our TSSOP24 semiconductor products. Total weight of the package varies depending on active die size. The material data is evidenced by written declaration from our packaging company. The products listed above DO NOT CONTAIN intentionally added hazardous materials such as cadmium (Cd), mercury (Hg), hexavalent chromium (Cr⁶⁺), polybrominated biphenyls (PBBs), polybrominated diphenylethers (PBDEs), bis(2-ethylhexyl) phthalate (DEHP), butyl benzyl phthalate (BBP), dibutyl phthalate (DBP), and diisobutyl phthalate (DIBP) except for 0.01 wt.% of lead (Pb), which **COMPLY with the RoHS3 Directive 2015/863/EU**. For further information, contact our Sales Department at sales@asb.co.kr.



Authorized Signature, ASB Inc.

This data is based on information provided by our suppliers and we do not validate it by measurement. ASB Inc. assumes no responsibility in connection with any use of this information. The information is subject to change without notice.
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